



US00D905021S

(12) **United States Design Patent** (10) **Patent No.:** **US D905,021 S**
Wengreen (45) **Date of Patent:** **** Dec. 15, 2020**

(54) **MOUNT FOR HEADPHONES**
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(72) Inventor: **Eric John Wengreen**, Sammamish, WA (US)

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(73) Assignee: **Innovelis, Inc.**, Sammamish, WA (US)
(**) Term: **15 Years**

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Headphone mount (ASIN B07PFV1N9X) available on Amazon.com prior to Oct. 2019, downloaded on Apr. 1, 2020 from <https://www.amazon.com/gp/product/B07PFV1N9X>.
Headphone mount (ASIN B01GJQ7N94) available on Amazon.com prior to Oct. 2019, downloaded on Apr. 1, 2020 from <https://www.amazon.com/gp/product/B01GJQ7N94>.

(21) Appl. No.: **29/712,007**
(22) Filed: **Nov. 5, 2019**
(51) **LOC (12) Cl.** **14-01**
(52) **U.S. Cl.**
USPC **D14/224**

(Continued)

Primary Examiner — Katie Jane Stofko

(58) **Field of Classification Search**
USPC D14/223–229; D16/244; D17/99;
D6/672, 681, 682, 526; 248/125.1, 166,
248/185.1; 381/355, 359, 361–363, 365,
381/366, 369, 375; 379/428.01, 428.04,
379/431, 433.03
CPC . H04R 25/00; H04R 1/02; H04R 5/02; H04R
9/08; F16M 11/38; F16M 13/00; F16M
11/00

(57) **CLAIM**

The ornamental design for a mount for headphones, as shown and described.

See application file for complete search history.

DESCRIPTION

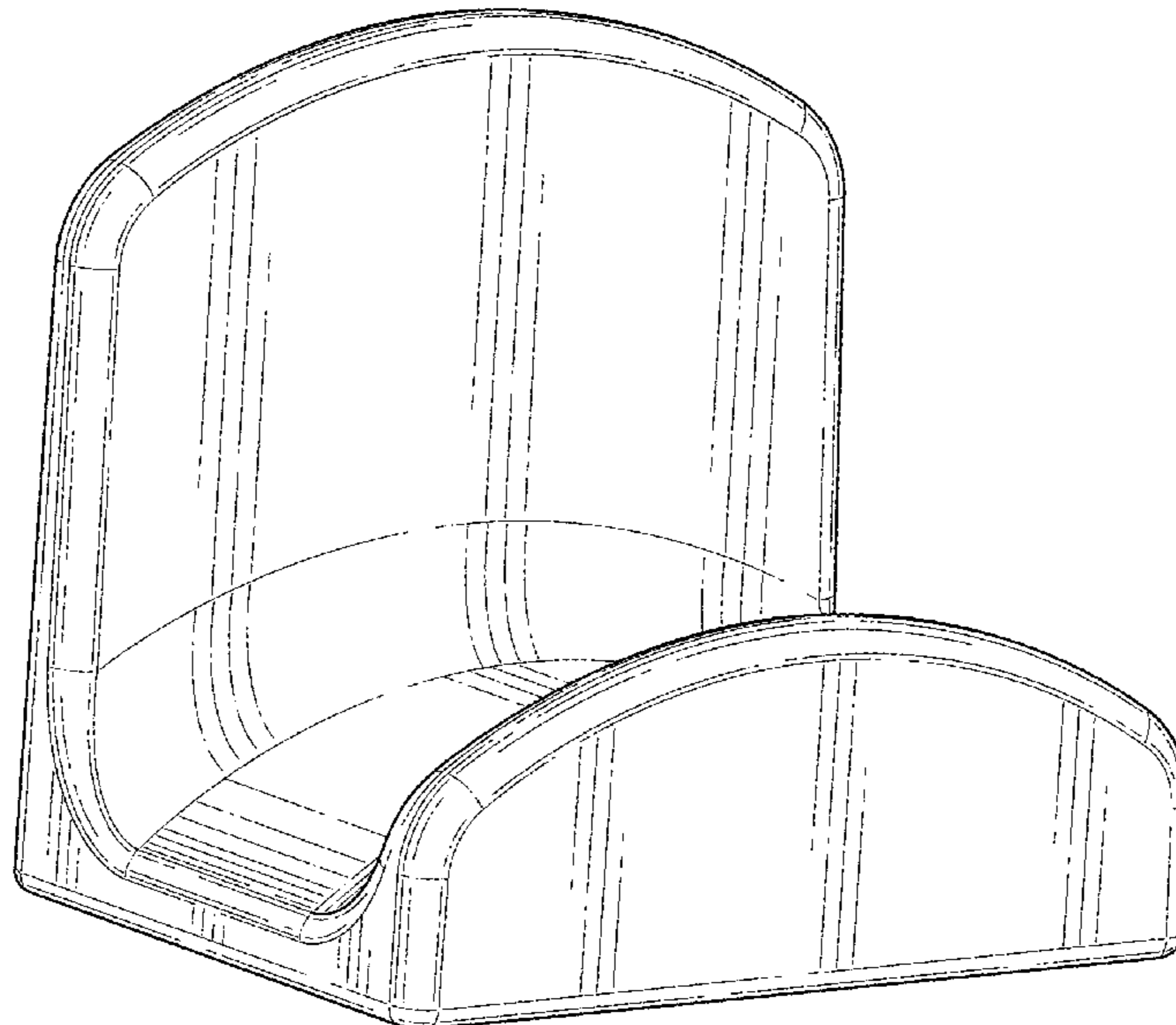
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FIG. 1 is a front, left side and top perspective view of a mount for headphones;
FIG. 2 is a back, right side and bottom perspective view thereof;
FIG. 3 is a front, left side and bottom perspective view thereof;
FIG. 4 is a right side elevation view thereof;
FIG. 5 is a left side elevation view thereof;
FIG. 6 is a top plan view thereof;
FIG. 7 is a bottom plan view thereof;
FIG. 8 is a front elevation view thereof; and,
FIG. 9 is a back elevation view thereof.
The broken lines shown in FIGS. 2, 3, 7 and 9 illustrate portions of the mount for headphones that form no part of the claimed design.

1 Claim, 9 Drawing Sheets



(56)

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Headphone mount (ASIN B07BVK2FQW) available on Amazon.com prior to Oct. 2019, downloaded on Apr. 1, 2020 from <https://www.amazon.com/gp/product/B07BVK2FQW>.

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Headphone mount (ASIN B012VIWG28) available on Amazon.com prior to Oct. 2019, downloaded on Apr. 1, 2020 from <https://www.amazon.com/gp/product/B012VIWG28>.

Headphone mount (ASIN B0192P8U5U) available on Amazon.com prior to Oct. 2019, downloaded on Apr. 1, 2020 from <https://www.amazon.com/gp/product/B0192P8U5U>.

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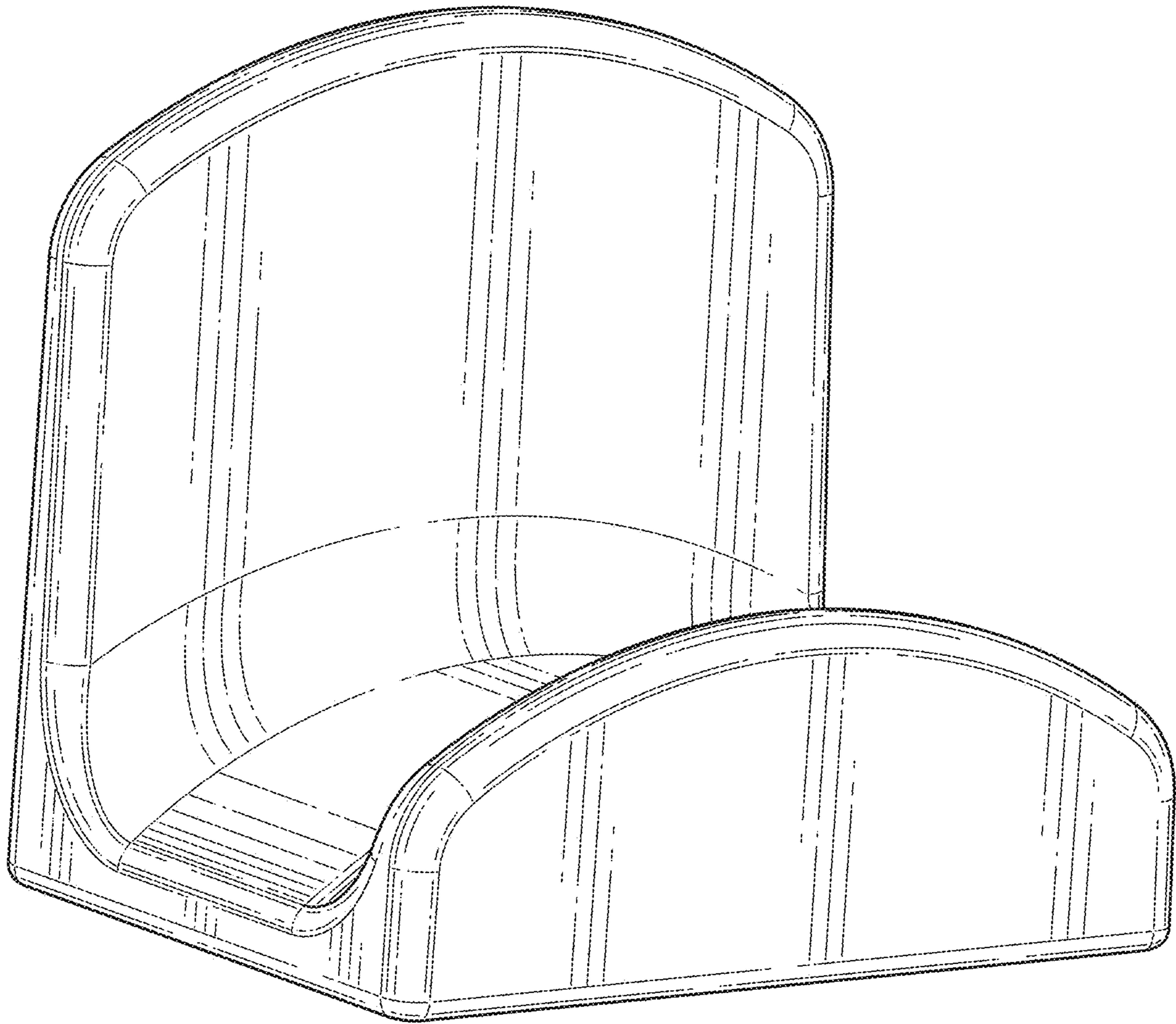


FIG. 1

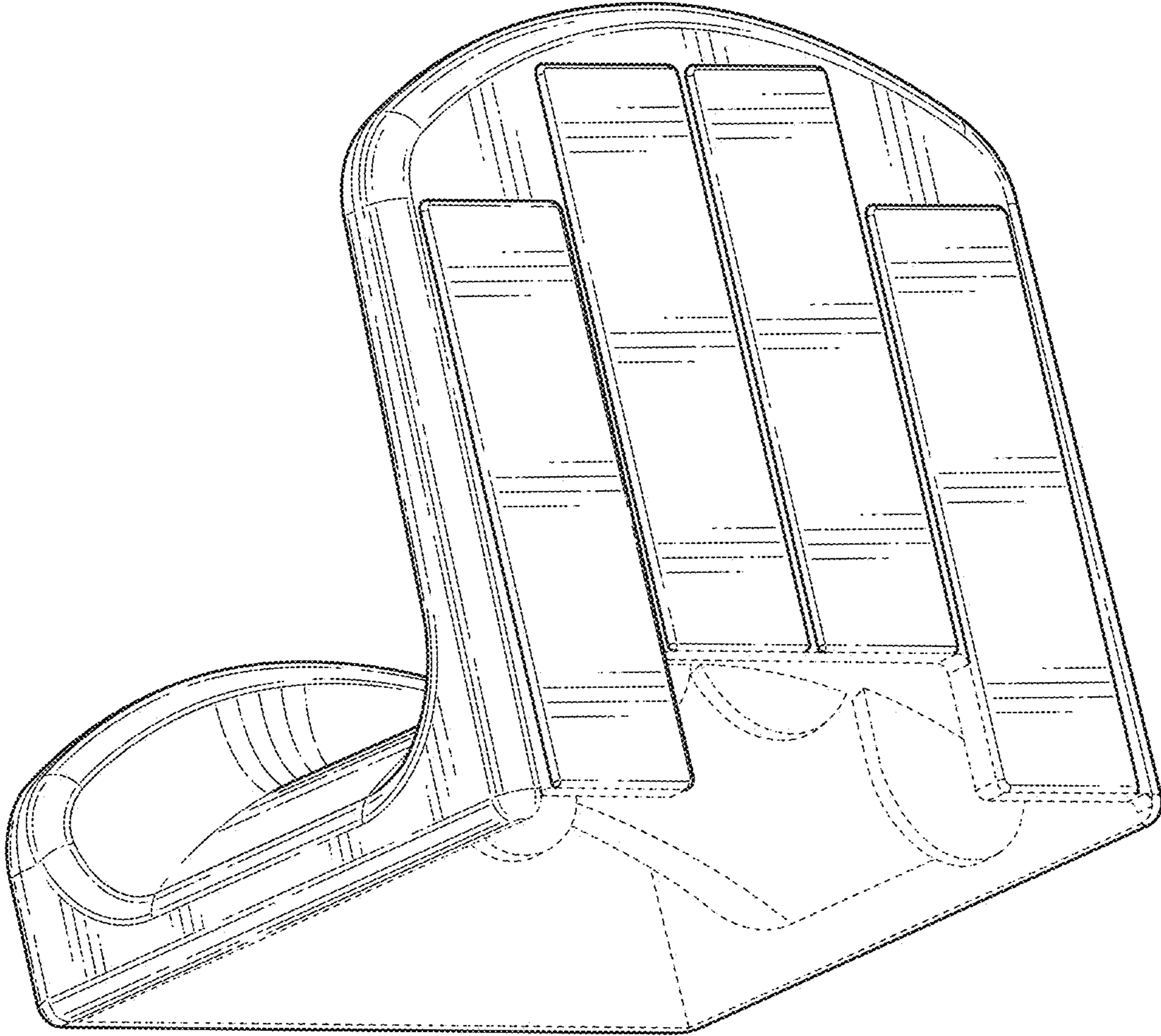


FIG. 2

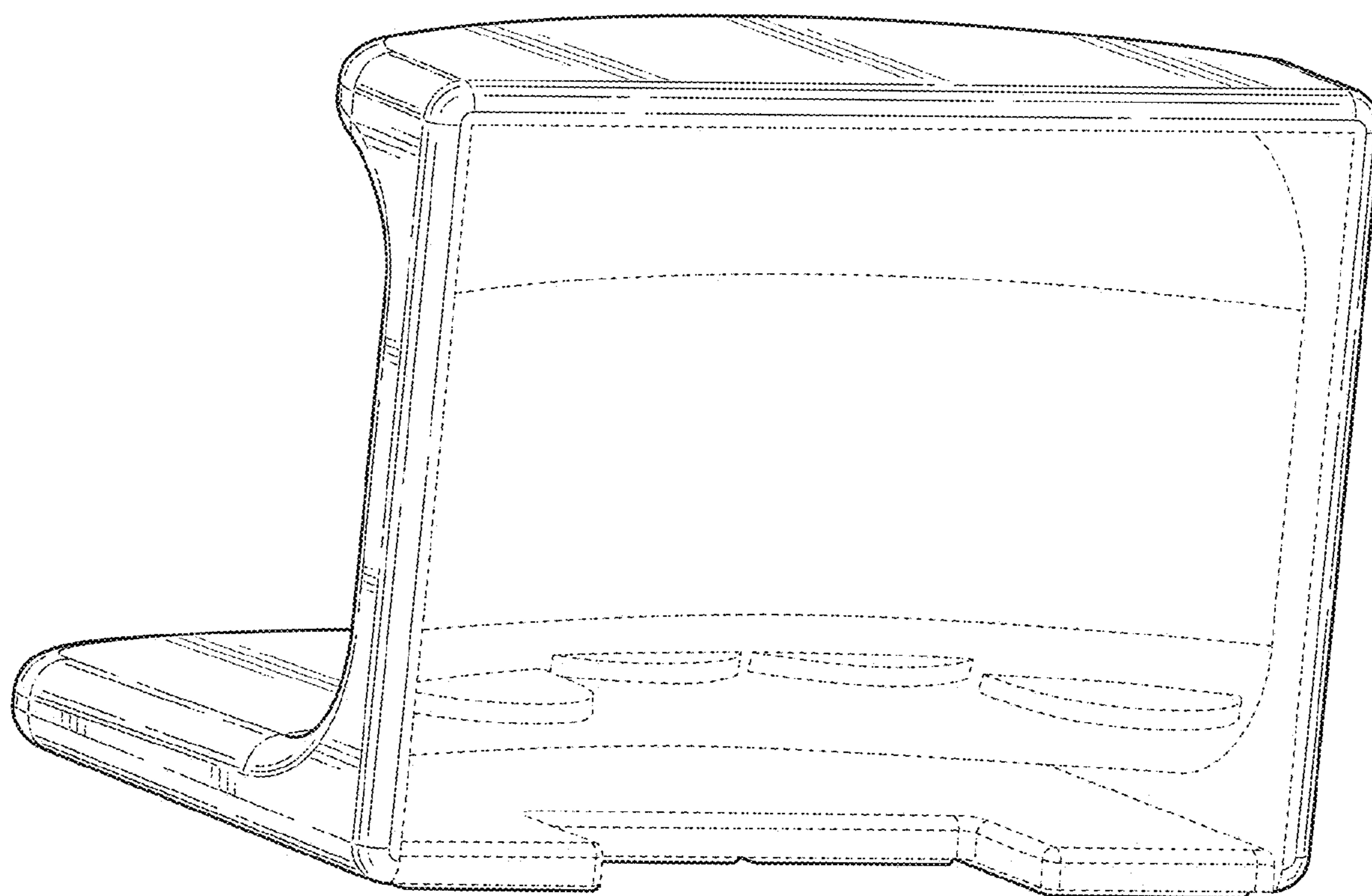


FIG. 3

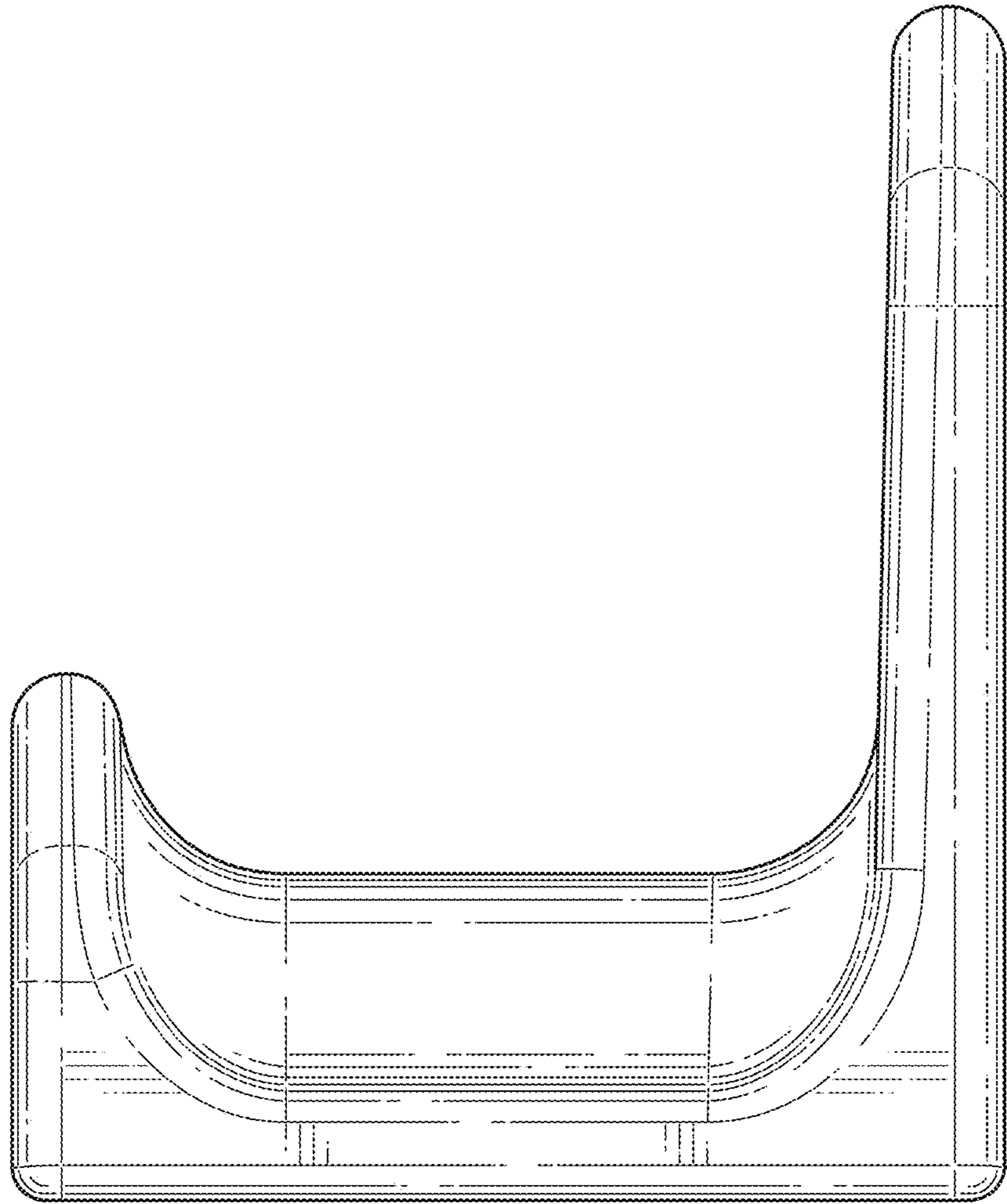


FIG. 4

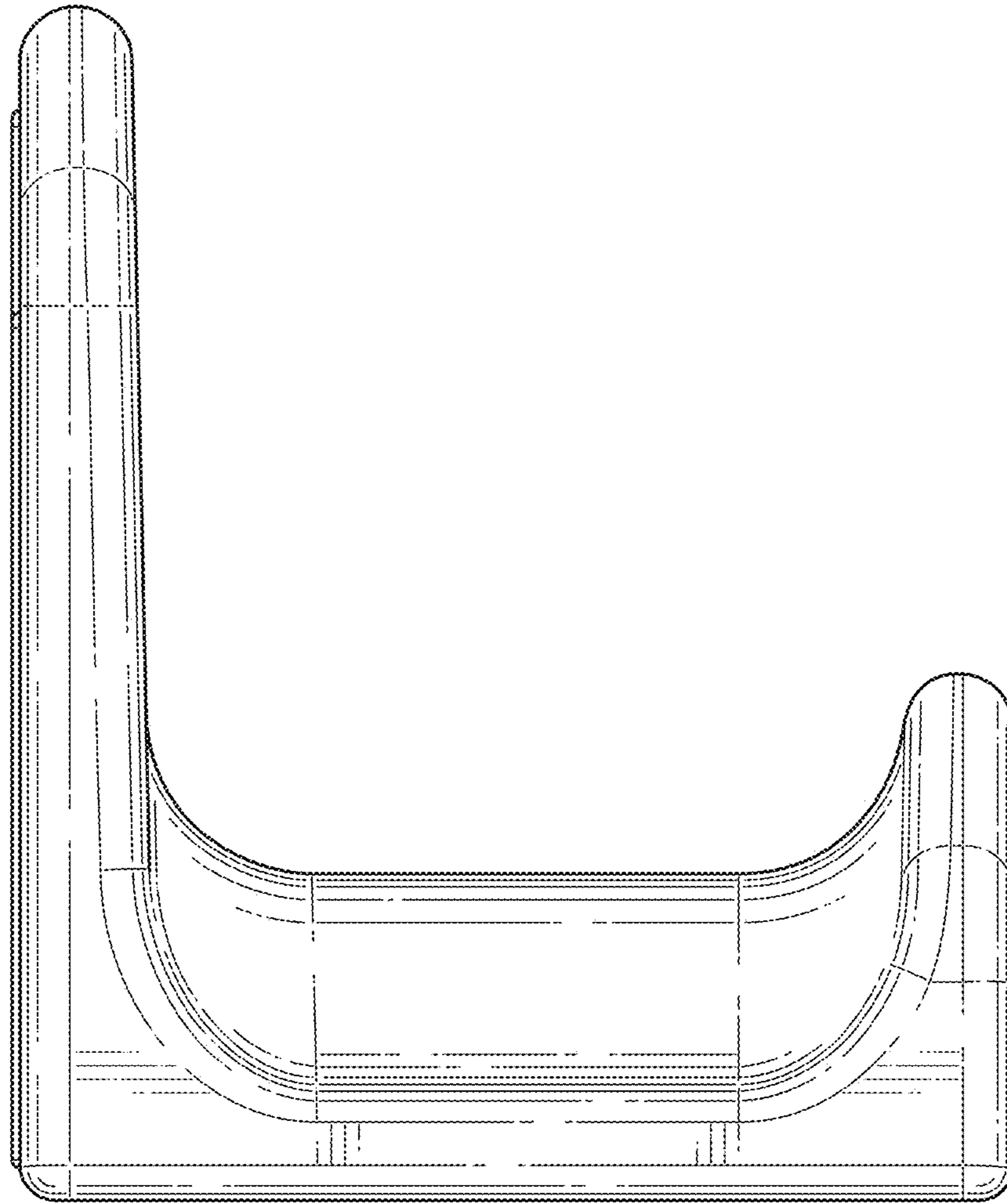


FIG. 5

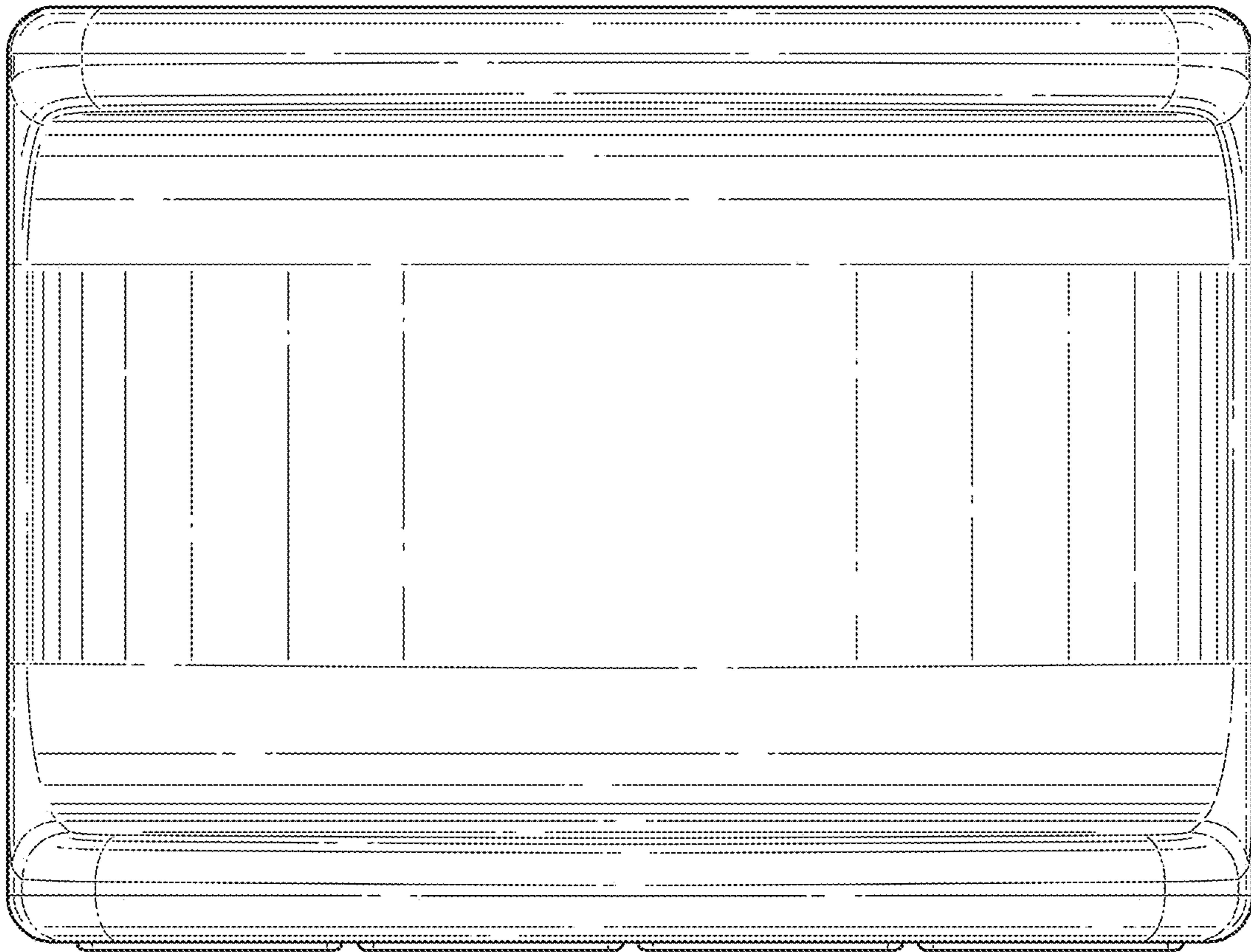


FIG. 6

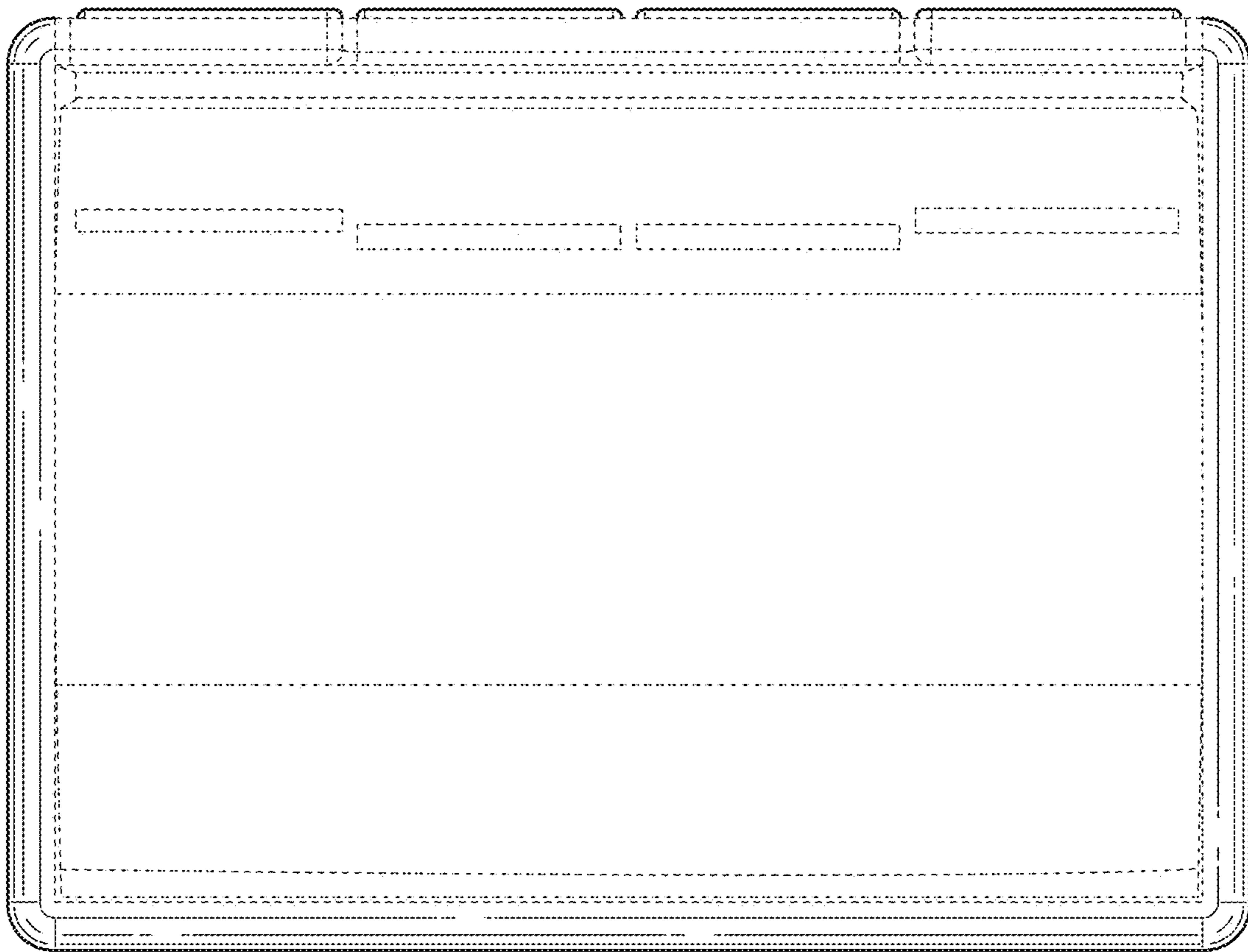


FIG. 7

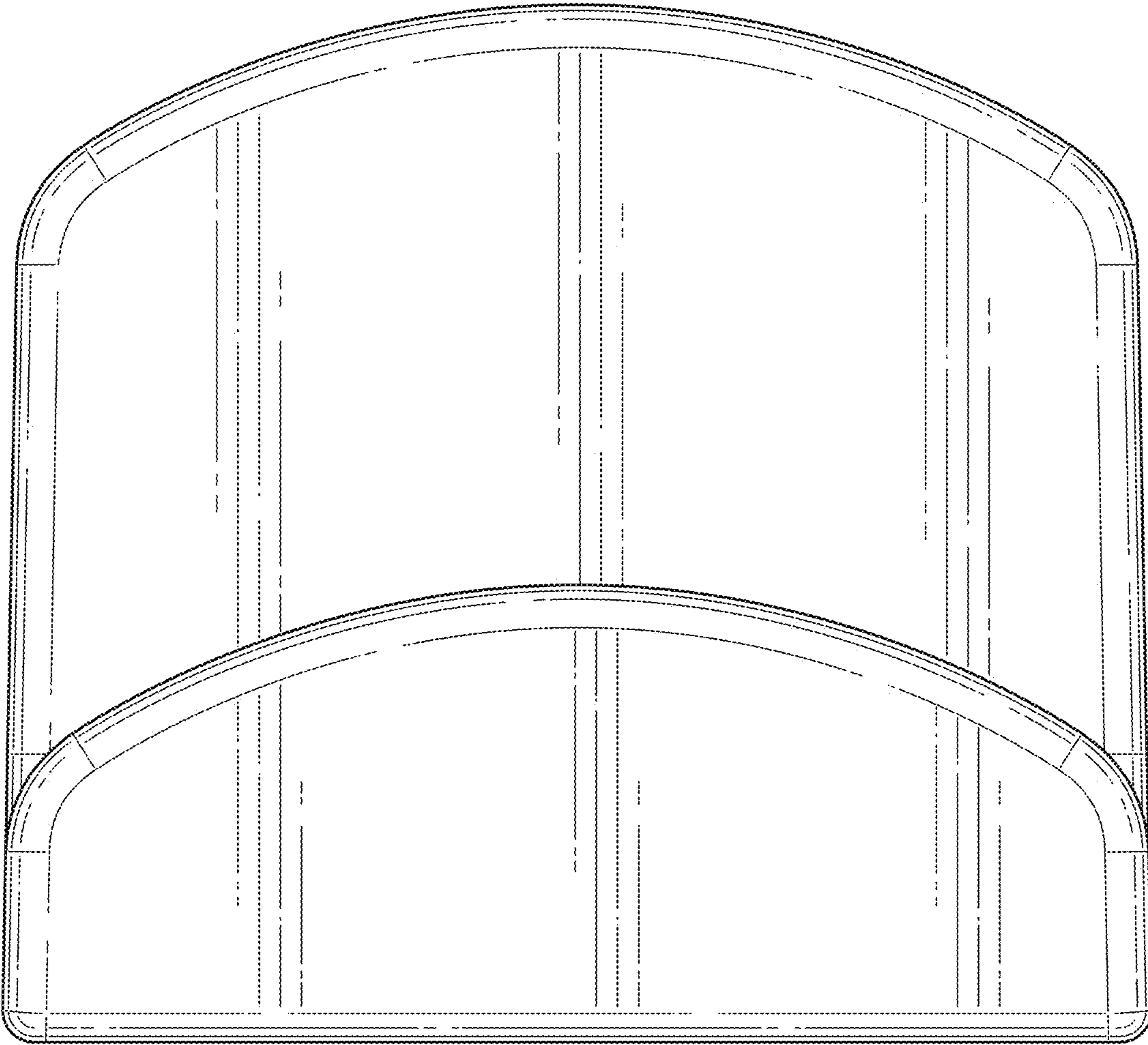


FIG. 8

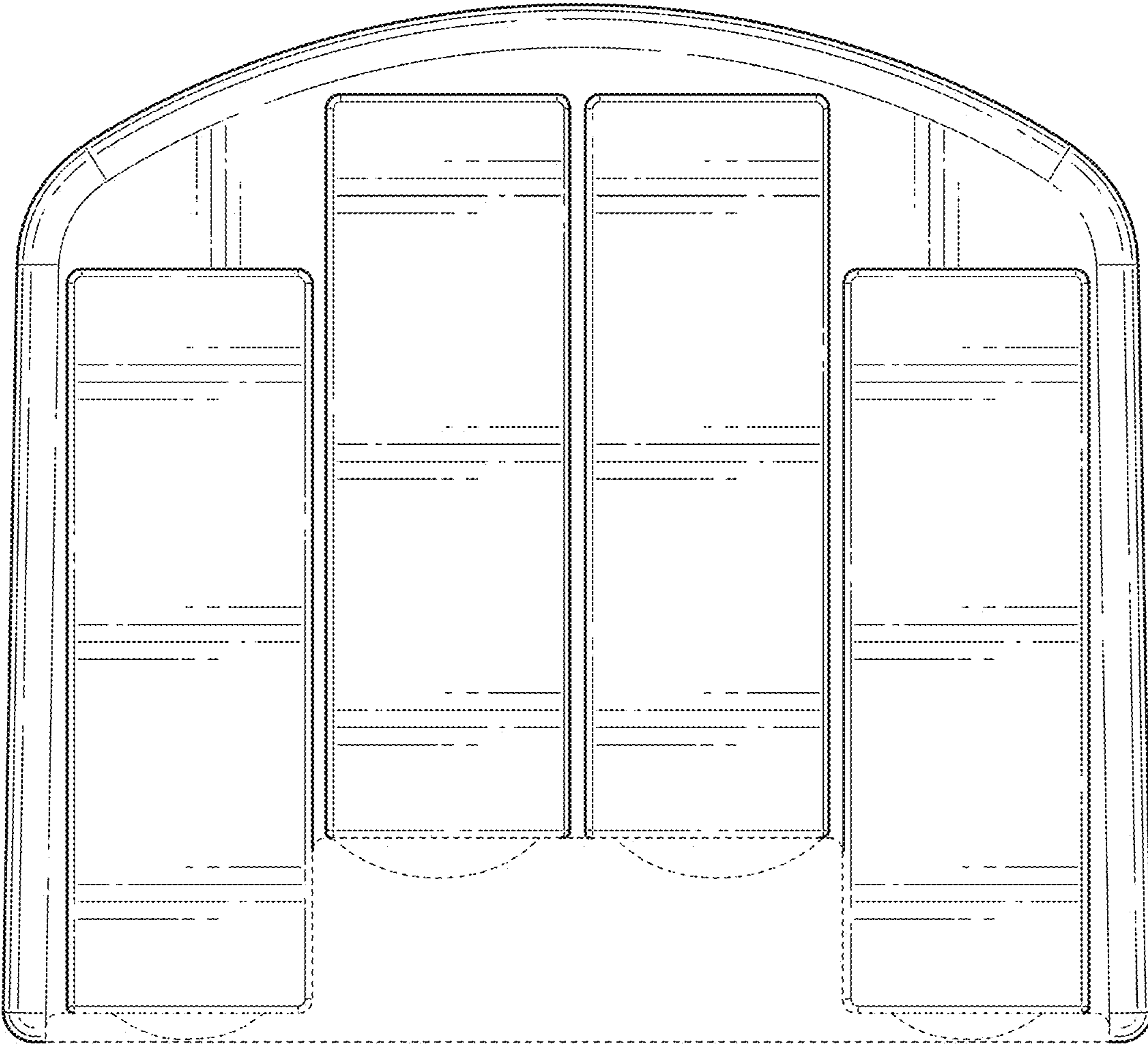


FIG. 9